| | |
|---|---|
| **Company :** | **Qualcomm** |
| **Company Name :** | **Qualcomm Technologies Inc** |
| **Nature Of Business :** | **Semiconductors** |
| **Designation :** | **Hardware Engineer** |
| Tentative Job Location : | Bangalore / Hyderabad /Chennai / Noida |

**Description :**

**We know our employees' ideas change the world. For more than three decades, we've been a global leader in mobile technology, continually pushing the boundaries of what's possible. Working with customers across industries — from automotive to health care, from smart cities to robotics— we continue to accelerate innovation and unlock new possibilities in a time where everything is connected. By joining the Qualcomm family, you too can bring the future forward faster.**

**Qualcomm is looking for an energetic, creative and self-driven engineer to work in Modem , Multimedia , Connectivity , Computer Vision and Image Processing , software implementation and hardware acceleration. The work will directly influence the various subsystems within the SoC. The ideal candidate would have very strong problem solving and analytical skills combined with creativity and a passion for innovation. They would be able to carry forward that new idea, concept, and/or application that will propel systems to new levels of effectiveness and efficiency. At Qualcomm you will perform detailed technical analysis, translate ideas into models, SW and/or HW and work closely with other teams to help deliver real products. At Qualcomm, the sky's the limit. College Graduates play important roles everywhere in the company. Many of our 27,000+ employees join us right out of school because we're working on the cutting edge in wireless. Complex wireless devices are only as powerful as the software that runs them. As a software engineer, you will develop, implement and maintain multimedia, gaming and application software for the world's leading-edge mobile devices. We know our employees' ideas change the world. For more than three decades, we've been a global leader in mobile technology, continually pushing the boundaries of what's possible. Working with customers across industries — from automotive to health care, from smart cities to robotics— we continue to accelerate innovation and unlock new possibilities in a time where everything is connected. By joining the Qualcomm family, you too can bring the future forward faster.**

**• SOC & Hard Macro Physical Design**

**• SOC Validation & Debug**

**• RF & Analog Layout**

**• RF/Analog/Mixed Signal/Power IC Design**

**• Low Power Design**

**• Board and FPGA Design**

**• Digital ASIC Design**

**• Design/SOC Verification**

**• CAD Solution Engineer**

**• Design for Test (DFT)**

**• CPU Desig**

**Must have educational background in one or more of the following areas:**

**• Verifying SoC with embedded RISC/DSP processors, communications/ networking ASICs.**

**• Verilog or VHDL, C/C++, Tcl/Perl/shell-scripting. RTL design experience and/or strong OO programming knowledge**

**• Knowledge of wireless/wired communications and protocols or graphics/video multimedia is a plus.**

**• Knowledge in PLL, LNA, OpAmp, CMOS, ADC/DAC, Cadence, SpectreRF, or Layout is required in RF/Analog/Mixed Signal IC Design.**

**• Excellent analytical and problem solving skills.**

**• Ability to collaborate and work in teams. • Good verbal and written communication skill**

**Educational Background: Masters, Bachelors: Electrical Engineering, VLSI , Embedded and VLSI ,**

**Eligibilty :**

| Program | AE | BSBE | CE | CHE | CSE | EE | ES | ME | MSE | PHY | CHM | MTH | ECO | DES | IME | CGS | HSS | EEM | MSP | NET | PSE | Stats |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| BT | No | No | No | No | No | Yes | -- | No | No | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- |
| BS | -- | -- | -- | -- | -- | -- | No | -- | -- | No | No | No | No | -- | -- | -- | -- | -- | -- | -- | -- | -- |
| MT | No | No | No | No | No | Yes | No | No | No | -- | -- | -- | -- | -- | No | -- | -- | No | No | No | No | -- |
| DoubleMajor | No | No | No | No | No | Yes | -- | No | No | No | No | No | No | -- | -- | -- | -- | -- | -- | -- | -- | -- |
| dual | No | No | No | No | No | Yes | No | No | No | No | No | No | No | -- | -- | -- | -- | -- | -- | -- | -- | -- |
| dualB | No | No | No | No | No | Yes | -- | No | No | No | No | No | No | -- | No | -- | -- | No | -- | No | No | -- |
| dualC | No | No | No | No | No | Yes | No | No | No | No | No | No | No | No | No | -- | -- | -- | -- | -- | -- | -- |
| Mdes | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | No | -- | -- | -- | -- | -- | -- | -- | -- |
| MBA | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | -- | No | -- | -- | -- | -- | -- | -- | -- |
| Phd | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No |

| | | | | | | | | | | | | | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| PhD | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No | No |
| MSc | -- | -- | -- | -- | -- | -- | -- | -- | -- | No | No | No | -- | -- | -- | -- | -- | -- | -- | -- | No |
| MSR | No | No | No | No | No | Yes | -- | No | No | -- | -- | -- | -- | -- | -- | No | -- | -- | -- | -- | No | -- |

**Cost to Company :** **---**

**Compensation For M.Tech Students(DD/ M.Tech/ MS by Research): Engineer**

| Component | Amount |
|---|---|
| Total Gross Pay | INR 12.50 L |
| Retirals (PF and Gratuity) | INR 0.75 L |
| Performance Bonus* | INR 0.70 L |
| Joining Bonus | INR 4.60 L |
| Relocation Bonus ( Paid within 60 days ) | INR 0.50 L |
| Restricted Stock Value Awards (Vesting in 3 years )** | INR 12.00 L ( $ 16000) |

***Based on individual & Organization Performance || **RSU -33% vesting every year**

**Additional Benefits : Relocation Assistance , Insurance , Transportation**

**$1= INR 75**

**Package Details :**

**Title : Associate Engineer || Degree : B.Tech**

**NEW**

| Component | Amount |
|---|---|
| Total Gross Pay | INR 11.50 L |
| Retirals (PF and Gratuity) | INR 0.69 L |
| Performance Bonus* | INR 0.70 L |
| Joining Bonus | INR 4.35 L |
| Relocation Bonus ( Paid within 60 days ) | INR 0.50 L |
| RSU - Restricted Stock Value Awards (Vesting in 3 years )** | INR 7.50 L ( $ 10000) |

***Based on Individual & Organization Performance || **RSU -33% vesting every year**

**Additional Benefits: Relocation Assistance, Insurance, Transportation.**

**$1=INR 75**

**Bond :** **False**

**CPI CutOff :** **0.0**

**Medical Requirments :**

**Resume Shortlist :** **False**

**Aptitude Test:** **False**

**Group Discussion:** **False**

**Technical Test:** **False**

**Technical Interview:** **False**

**HR Interview:** **False**

**Additional Information:**